



Material Content Data Sheet



Sales Product Name		1EDI20I12MF		Issued		20. July 2018		
MA#		MA001245994						
Package		PG-DSO-8-51		Weight*		80.43 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.400	2.98	2.98	29841	29841
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		103	
	non noble metal	zinc	7440-66-6	0.033	0.04		410	
	non noble metal	iron	7439-89-6	0.660	0.82		8203	
wire	non noble metal	copper	7440-50-8	26.789	33.31	34.18	333079	341795
	noble metal	gold	7440-57-5	0.228	0.28	0.28	2831	2831
	encapsulation	organic material	carbon black	1333-86-4	0.146	0.18		1811
plastics		epoxy resin	-	4.709	5.86		58551	
	inorganic material	silicondioxide	60676-86-0	43.694	54.33	60.37	543253	603615
leadfinish	non noble metal	tin	7440-31-5	0.814	1.01	1.01	10119	10119
plating	noble metal	silver	7440-22-4	0.095	0.12	0.12	1184	1184
glue	plastics	acrylic resin	-	0.188	0.23		2335	
	noble metal	silver	7440-22-4	0.666	0.83	1.06	8280	10615
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com